

**FOR ADDITIONAL INFORMATION
CONTACT:**

Technical Support

Phone: (518) 452-2880

E-mail: info@yincae.com



YINCAE Advanced Materials, LLC

19 Walker Way, Albany, NY 12205

(518) 452-2880

www.yincae.com

FOR IMMEDIATE RELEASE

Press Release

**IPC APEX EXPO 2016
VISIT YINCAE BOOTH 1718**

Join Dr. Yin's Presentation on March 17th from 9AM-10AM

(Albany, NY) **February 9, 2016** – The *IPC APEX EXPO 2016* hosted by the Las Vegas Convention Center from March 15th – 17th is only one month away! This year's *Forward Thinking for Tomorrow's Technology* theme will offer unparalleled opportunities to access solutions to industry experts. We look forward for you to stop by our **Booth 1718** to learn more about the innovative products and custom solutions that we offer.

On **Thursday, March 17th, 2016 from 9:00AM – 10:00 AM**, Dr. Yin will be presenting his paper, **“Can Lower Temperature Solderable Adhesive Replace SAC Paste?”** He will not only discuss the development of low temperature solderable adhesives to replace SAC applications, but the myriad of benefits for use across industry domains. The low temperature solderable adhesives can be used anywhere, particularly for wafer-level (CSP), package-level, and board-level (LGA, BGA, and QFN) to name a few. The low temperature solderable adhesive has improved drop performance by two magnitudes compared to Sn/Bi alloy and has improved reliability by equal or better than that of SAC alloy.

We at YINCAE Advanced Materials, LLC hope you will join us to learn about YINCAE and the exclusive products that you will not find with any other manufacturer in the world. **We look forward to seeing you at booth 1718!**

For more information, please visit our website: www.yincae.com

* * * * *

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

###

The YINCAE brand name and logo are trademarks of YINCAE Advanced Materials, LLC.